Advanced packaging for photonics, optics and electronics for low cost manufacturing in Europe

Results

Project Information

**APPLAUSE**

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Publications

Conference proceedings (4)

- Simulated effects of wet-etched induced surface roughness on IR transmission and reflection
  
  **Author(s):** Phillip Papatzacos, M. Nadeem Akram, Eivind Bardalen, Per Ohlickers
  
  **Published in:** 2020 IEEE 8th Electronics System-Integration Technology Conference (ESTC), 2020, Page(s) 1-4
  
  **DOI:** 10.1109/estc48849.2020.9229821

- High-speed ultra-accurate direct C2W bonding
Study of Cu-Sn-In system for low temperature, wafer level solid liquid inter-diffusion bonding

Author(s): Birgit Brandstatter, Daniel Aschenwald, Benedikt Auer, Norbert Bilewicz, Ruurd Boomsma, Christoph Kroll, Andreas Mayr, Richard Neumayr, Hannes Rieser, Mario Scherntthaner, Hubert Selhofer, Florian Speer, Peter Unterwaditzer, Andras Videki, Martin Widauer, Thomas Widmann

Published in: 2020 IEEE 70th Electronic Components and Technology Conference (ECTC), 2020, Page(s) 1943-1949

DOI: 10.1109/ectc32862.2020.00303

Evaluation of Silicon Diaphragms for Hermetic Packaging of Microbolometer Arrays

Author(s): Joseph Hotchkiss, Vesa Vuorinen, Hongqun Dong, Glenn Ross, Jani Kaaos, Mervi Paulasto-Kröckel, Tobias Wernicke, Anneliese Ponninger

Published in: 2020 IEEE 8th Electronics System-Integration Technology Conference (ESTC), 2020, Page(s) 1-5

DOI: 10.1109/estc48849.2020.9229696

Versatile Externally Modulated Lasers Technology for Multiple Telecommunication Applications

Author(s): Xing Dai, Helene Debregeas, Guillaume Da Rold, David Carrara, Kevin Louarn, Elena Duran Valdeiglesias, Francois Lelarge

Published in: IEEE Journal of Selected Topics in Quantum Electronics, Issue 27/3, 2021, Page(s) 1-12, ISSN 1077-260X

DOI: 10.1109/jstqe.2020.3029394

Wafer Level Solid Liquid Interdiffusion Bonding: Formation and Evolution of Microstructures

Author(s): V. Vuorinen, H. Dong, G. Ross, J. Hotchkiss, J. Kaaos, M. Paulasto-Kröckel

Published in: Journal of Electronic Materials, 2020, ISSN 0361-5235

DOI: 10.1007/s11664-020-08530-y

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